

TSM100N0660V N-Channel Power MOSFET







Pin Definition:

- 1. Gate
- 2. Drain3. Source

PRODUCT SUMMARY

V _{DS} (V)	$V_{DS}(V)$ $R_{DS(on)}(m\Omega)$	
60	6.7 @ V _{GS} =10V	100

Features

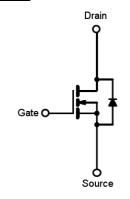
- Advanced Trench Technology
- Low $R_{DS(ON)}$ 6.7m Ω (Max.)
- Low gate charge typical @ 81nC (Typ.)
- Low Crss typical @ 339pF (Typ.)

Ordering Information

Part No.	Package	Packing
TSM100N06CZ C0G	TO-220	50pcs / Tube

Note: "G" denote for Halogen Free Product

Block Diagram



N-Channel MOSFET

Absolute Maximum Rating (Ta = 25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V_{GS}	±20	V	
	T _C =25°C		100 ⁽³⁾	А	
Continuous Drain Current	T _C =70°C		80		
Continuous Drain Current	T _A =25°C	l _D	14		
	T _A =70°C		11		
Drain Current-Pulsed Note 1		I _{DM}	400	Α	
Avalanche Current, L=0.1mH		I _{AS}	71	Α	
Avalanche Energy, L=0.1mH		E _{AS} , E _{AR}	400	mJ	
	T _C =25°C		167		
Mayimum Dayyar Dissination	T _C =70°C	Б	107	W	
Maximum Power Dissipation	T _A =25°C	P_{D}	2		
	T _A =70°C		1.3		
Storage Temperature Range		T _{STG}	-55 to +150	°C	
Operating Junction Temperature Range	·	T_J	-55 to +150	°C	

^{*} Limited by maximum junction temperature

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance - Junction to Case	$R\Theta_{JC}$	0.8	°C/W
Thermal Resistance - Junction to Ambient	R⊖ _{JA}	62.5	°C/W

Notes: Surface mounted on FR4 board t ≤ 10sec



60V N-Channel Power MOSFET



Electrical Specifications (Ta = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250uA$	BV _{DSS}	60			V
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 30A$	R _{DS(ON)}		5.7	6.7	mΩ
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250uA$	$V_{GS(TH)}$	2	3	4	V
Zero Gate Voltage Drain Current	$V_{DS} = 48V, V_{GS} = 0V$	I _{DSS}			1	uA
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
Dynamic						
Total Gate Charge	V 00V I 00A	Q_g		81		
Gate-Source Charge	$V_{DS} = 30V, I_{D} = 30A,$	Q_gs	1	23		nC
Gate-Drain Charge	$V_{GS} = 10V$	Q_{gd}	1	24		
Input Capacitance	V 20V V 0V	C _{iss}	1	4382		
Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$	C _{oss}		668		рF
Reverse Transfer Capacitance	f = 1.0MHz	C _{rss}		339		
Switching						
Turn-On Delay Time		t _{d(on)}	1	25		
Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 30V,$	t _r		19		0
Turn-Off Delay Time	$R_G = 3.3\Omega$	t _{d(off)}		85		nS
Turn-Off Fall Time		t _f		43		
Drain-Source Diode Characteristics and Maximum Rating						
Drain-Source Diode Forward Voltage	V _{GS} =0V, I _S =20A	V _{SD}	-	0.8	1.3	V
Reverse Recovery Time	$I_S = 30A, T_J = 25$ °C	t _{fr}		36		nS
Reverse Recovery Charge	dl/dt = 100A/us	Q _{fr}		53		nC

Notes:

- 1. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 2. $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\Theta JC}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. $R_{\Theta JA}$ shown below for single device operation on FR-4 in still air
- 3. Calculated continuous current based on maximum allowable junction temperature, Package limitation current is 75A

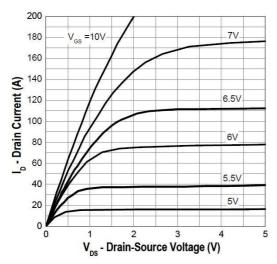


60V N-Channel Power MOSFET

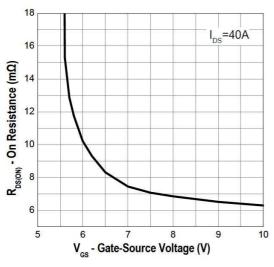


Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)

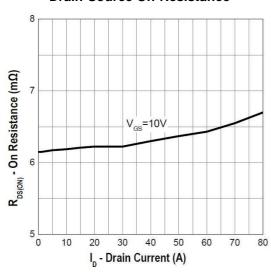
Output Characteristics



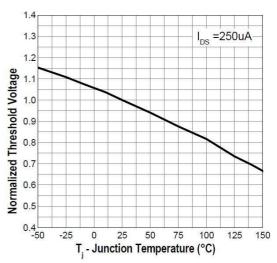
Gate Source On Resistance



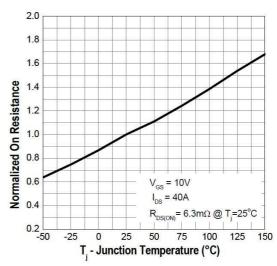
Drain-Source On-Resistance



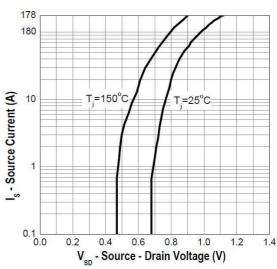
Gate Threshold Voltage



Drain-Source On Resistance



Source-Drain Diode Forward Voltage



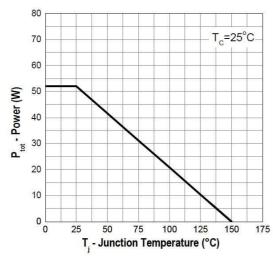


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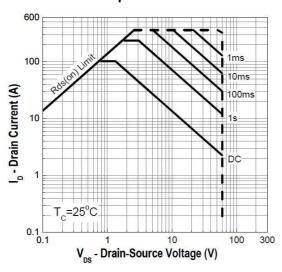


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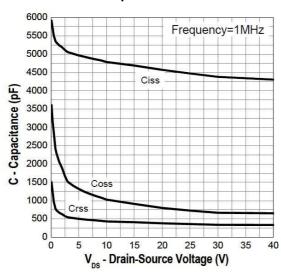




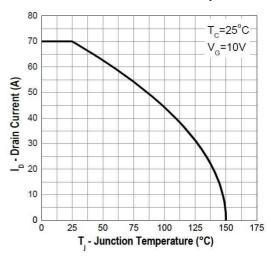
Safe Operation Area



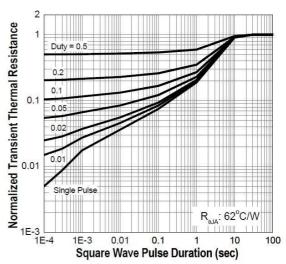
Capacitance



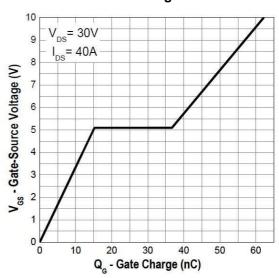
Drain Current vs. Junction Temperature



Transient Thermal Impedance



Gate Charge

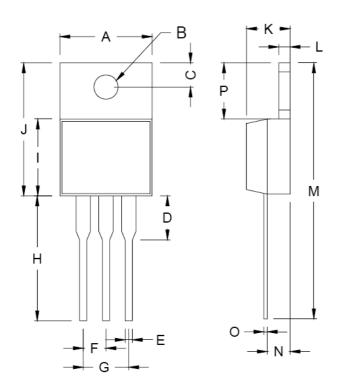




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TO-220 Mechanical Drawing



TO-220 DIMENSION					
DIM	MILLIM	ETERS	INCHES		
DIIVI	MIN	MAX	MIN	MAX	
Α	10.000	10.500	0.394	0.413	
В	3.740	3.910	0.147	0.154	
С	2.440	2.940	0.096	0.116	
D	-	6.350	-	0.250	
Е	0.381	1.106	0.015	0.040	
F	2.345	2.715	0.092	0.058	
G	4.690	5.430	0.092	0.107	
Н	12.700	14.732	0.500	0.581	
J	14.224	16.510	0.560	0.650	
K	3.556	4.826	0.140	0.190	
L	0.508	1.397	0.020	0.055	
М	27.700	29.620	1.060	1.230	
N	2.032	2.921	0.080	0.115	
0	0.255	0.610	0.010	0.024	
Р	5.842	6.858	0.230	0.270	



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